# **Special Issue**

# New Frontiers in Magnetic Polishing and Electrochemical Technology

### Message from the Guest Editors

This special issue welcomes novel processing research submissions, such as miniaturization, precision, composite, intelligent, multiple physical coupling, simulation analysis, difficult-to-machine appearance and inner hole feature processing, new material processing technology, etc., we hope that experts and scholars can contribute your researches to this special issue. Thanks a lot.

### **Guest Editors**

Prof. Dr. A-Cheng Wang

Department of Mechanical Engineering, Chien Hsin University of Science and Technology, Taoyuan 320, Taiwan

Prof. Dr. Jung-Chou Hung

Department of Mechanical Engineering, National Central University, Taoyuan 32001, Taiwan

### Deadline for manuscript submissions

closed (30 April 2022)



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Prof. Dr. Giancarlo Cravotto

Department of Drug Science and Technology, University of Turin, Via P. Giuria 9, 10125 Turin, Italy

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